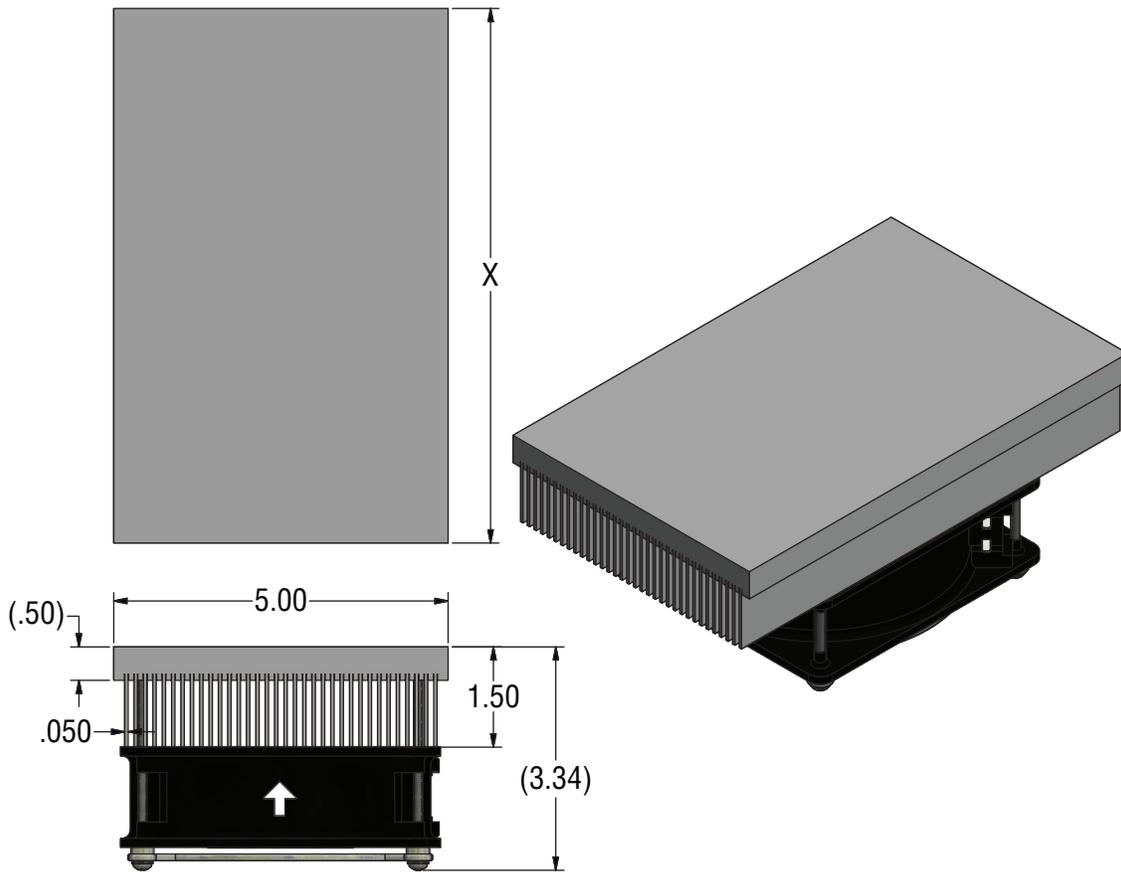


IMPINGEMENT HEAT SINK

Ideal for IGBT and power MOSFET applications as well as Diode and SCR Bridges. The impingement cooling allows modules to be mounted close together while keeping an extremely low cost per watt. This results in all modules in a system to operate at the same temperature increasing system reliability. Additionally, the close mounting structure allows for shorter bus bars that reduces cost and lowers circuit inductance. The impingement style Heat Sinks provide very high performance cooling in a small package. **Custom designs are available upon request.**



POWER-PAK IMPINGEMENT COOLING

MODEL #	CH6500F	CH6600F
Dimension X	5.00"	8.00"
Thermal Resistance	0.10°C/W	0.08°C/W

Thermal performances based on 100 CFM fan. Mounting pattern shown fits standard "muffin" fans.